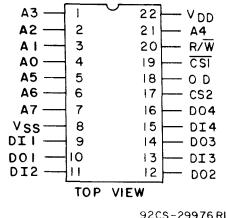


**MWS5101A****TERMINAL ASSIGNMENT**

The RCA-MWS5101A is a 256-word by 4-bit static random-access memory designed for use in memory systems where high speed, very low operating current, and simplicity in use are desirable. It has separate data inputs and outputs and utilizes a single power supply of 4 to 6.5 volts.

Two Chip-Select inputs are provided to simplify system expansion. An Output Disable control provides Wire-OR capability and is also useful in common Input/Output systems. The Output Disable input allows these RAM's to be used in common data Input/Output systems by forcing the output into a high-impedance state during a write operation independent of the Chip-Select input condition. The output

## 256-Word by 4-Bit LSI Static Random-Access Memory

**Features:**

- Industry standard pinout
- Very low operating current—8 mA at  $V_{DD} = 5$  V and cycle time = 1  $\mu$ s
- Two Chip-Select inputs—simple memory expansion
- Memory retention for standby battery voltage of 2 V min.
- TTL compatible
- Output-Disable for common I/O systems
- 3-state data output for bus-oriented systems
- Separate data inputs and outputs

assumes a high-impedance state when the Output Disable is at high level or when the chip is deselected by CS1 and/or CS2

For applications requiring CMOS compatibility over wider operating voltage and temperature ranges, the mechanical and functional equivalent RCA-CDP1822 static RAM may be used

The MWS5101A types are supplied in 22-lead hermetic dual-in-line, side-brazed ceramic packages (D suffix), in 22-lead dual-in-line plastic packages (E suffix), and in chip form (H suffix).

**OPERATIONAL MODES**

MODE	INPUTS				OUTPUT
	Chip Select 1 CS1	Chip Select 2 CS2	Output Disable OD	Read/Write R/W	
READ	0	1	0	1	Read
WRITE	0	1	0	0	Data In
WRITE	0	1	1	0	High Impedance
STANDBY	1	X	X	X	High Impedance
STANDBY	X	0	X	X	High Impedance
OUTPUT DISABLE	X	X	1	X	High Impedance

Logic 1 = High

Logic 0 = Low

X = Don't Care

**OPERATING CONDITIONS at  $T_A$  = Full Package-Temperature Range**  
*For maximum reliability, operating conditions should be selected so that operation is always within the following ranges:*

CHARACTERISTIC	LIMITS		UNITS	
	ALL TYPES			
	Min.	Max.		
DC Operating-Voltage Range	4	6.5		
Input Voltage Range	V <sub>SS</sub>	V <sub>DD</sub>	V	

**MAXIMUM RATINGS, Absolute-Maximum Values:**DC SUPPLY-VOLTAGE RANGE (V<sub>DD</sub>)(All voltage referenced to V<sub>SS</sub> terminal) ..... -0.5 to -7 VINPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5 to V<sub>DD</sub> + 0.5 V

DC INPUT CURRENT, ANY ONE INPUT ..... ± 10 mA

POWER DISSIPATION PER PACKAGE (P<sub>D</sub>)'For T<sub>A</sub> = -40 to +60°C (PACKAGE TYPE E) ..... 500 mWFor T<sub>A</sub> = +60 to +85°C (PACKAGE TYPE E) ..... Derate Linearly at 12 mW/°C to 200 mWFor T<sub>A</sub> = -55 to +100°C (PACKAGE TYPE D) ..... 500 mWFor T<sub>A</sub> = +100 to +125°C (PACKAGE TYPE D) ..... Derate Linearly at 12 mW/°C to 200 mW

## DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR T<sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) ..... 100 mWOPERATING-TEMPERATURE RANGE (T<sub>A</sub>).

PACKAGE TYPE D ..... -55 to +125°C

PACKAGE TYPE E ..... -40 to +85°C

STORAGE TEMPERATURE RANGE (T<sub>SIG</sub>) ..... -65 to +150°C

## LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 ± 1/32 inch (1.59 ± 0.79 mm) from case for 10 s max. ..... +265°C

**STATIC ELECTRICAL CHARACTERISTICS at  $T_A$  = 0 to 70°C, V<sub>DD</sub> = 5 V**

CHARACTERISTIC	TEST CONDITIONS		LIMITS			UNITS	
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	MWS5101AD MWS5101AE				
			Min.	Typ.*	Max.		
Quiescent Device Current, I <sub>DD</sub>	L2 Types	—	0, 5	—	25	50	
	L3 Types	—	0, 5	—	100	200	
Output Voltage:							
Low-Level,                      V <sub>OL</sub>	—	0, 5	—	0	0.1	V	
High-Level,                     V <sub>OH</sub>	—	0, 5	4.9	5	—		
Input Low Voltage,              V <sub>IL</sub>	—	—	—	—	0.65		
Input High Voltage,            V <sub>IH</sub>	—	—	2.2	—	—		
Output Low (Sink) Current,    I <sub>OL</sub>	0.4	0, 5	2	4	—	mA	
Output High (Source) Current, I <sub>OH</sub>	4.6	0, 5	-1	-2	—		
Input Current,                I <sub>IN</sub>	—	0, 5	—	—	±5	μA	
3-State Output Leakage Current,                      I <sub>OUT</sub>	L2 Types	0, 5	0, 5	—	—		
	L3 Types	0, 5	0, 5	—	—	±5	
Operating Current,            I <sub>DD1</sub> #	—	0, 5	—	4	8	mA	
Input Capacitance,            C <sub>IN</sub>	—	—	—	5	7.5	pF	
Output Capacitance,          C <sub>OUT</sub>	—	—	—	10	15		

\*Typical values are for T<sub>A</sub> = 25°C and nominal V<sub>DD</sub>.

#Outputs open-circuited; cycle time = 1 μs.

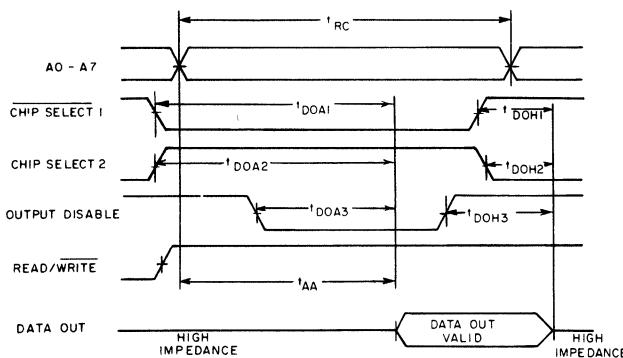
**MWS5101A**

**DYNAMIC ELECTRICAL CHARACTERISTICS** at  $T_A = 0$  to  $70^\circ\text{C}$ ,  $V_{DD} = 5\text{ V} \pm 5\%$ ,  
 $t_r, t_f = 20\text{ ns}$ ,  $C_L = 50\text{ pF}$  and 1 TTL Load

CHARACTERISTIC	LIMITS						UNITS	
	MWS5101AD, MWS5101AE							
	L2 Types			L3 Types				
	Min. <sup>†</sup>	Typ. <sup>*</sup>	Max.	Min. <sup>†</sup>	Typ. <sup>*</sup>	Max.		
<b>Read Cycle Times (Fig. 1)</b>								
Read Cycle	t <sub>RC</sub>	250	—	—	350	—	—	
Access from Address	t <sub>AA</sub>	—	150	250	—	200	350	
Output Valid from Chip-Select 1	t <sub>DOA1</sub>	—	150	250	—	200	350	
Output Valid from Chip-Select 2	t <sub>DOA2</sub>	—	150	250	—	200	350	
Output Valid from Output Disable	t <sub>DOA3</sub>	—	—	110	—	—	150	
Output Hold from Chip-Select 1	t <sub>DOH1</sub>	20	—	—	20	—	—	
Output Hold from Chip-Select 2	t <sub>DOH2</sub>	20	—	—	20	—	—	
Output Hold from Output Disable	t <sub>DOH3</sub>	20	—	—	20	—	—	

<sup>†</sup>Time required by a limit device to allow for the indicated function.

<sup>\*</sup>Typical values are for  $T_A = 25^\circ\text{C}$  and nominal  $V_{DD}$ .



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Fig. 1 - Read cycle timing waveforms

**MWS5101A**

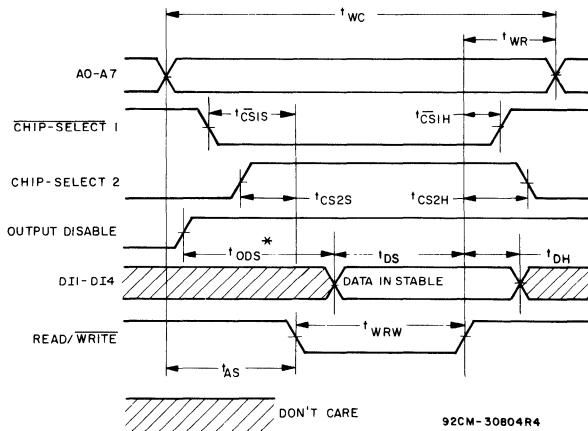
**DYNAMIC ELECTRICAL CHARACTERISTICS** at  $T_A = 0$  to  $70^\circ\text{C}$ ,  $V_{DD} = 5\text{ V} \pm 5\%$ ,  
 $t_r, t_f = 20\text{ ns}$ ,  $C_L = 50\text{ pF}$  and 1 TTL Load

CHARACTERISTIC	LIMITS						UNITS	
	MWS5101AD, MWS5101AE							
	L2 Types			L3 Types				
	Min. <sup>†</sup>	Typ.*	Max.	Min. <sup>†</sup>	Typ.*	Max.		
<b>Write Cycle Times (Fig. 2)</b>								
Write Cycle	$t_{WC}$	300	—	—	400	—	—	
Address Setup	$t_{AS}$	110	—	—	150	—	—	
Write Recovery	$t_{WR}$	40	—	—	50	—	—	
Write Width	$t_{WRW}$	150	—	—	200	—	—	
Input Data Setup Time	$t_{DS}$	150	—	—	200	—	—	
Data In Hold	$t_{DH}$	40	—	—	50	—	—	
Chip-Select 1 Setup	$t_{CS1S}$	110	—	—	150	—	—	
Chip-Select 2 Setup	$t_{CS2S}$	110	—	—	150	—	—	
Chip-Select 1 Hold	$t_{CS1H}$	0	—	—	0	—	—	
Chip-Select 2 Hold	$t_{CS2H}$	0	—	—	0	—	—	
Output Disable Setup	$t_{ODS}$	110	—	—	150	—	—	

<sup>†</sup>Time required by a limit device to allow for the indicated function.

\*Typical values are for  $T_A = 25^\circ\text{C}$  and nominal  $V_{DD}$ .

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\*  $t_{ODS}$  IS REQUIRED FOR COMMON I/O  
 OPERATION ONLY, FOR SEPARATE I/O  
 OPERATIONS, OUTPUT DISABLE IS DON'T CARE

Fig. 2 - Write cycle timing waveforms

**MWS5101A**DATA RETENTION CHARACTERISTICS at  $T_A = 0$  to  $70^\circ\text{C}$ ; See Fig. 3.

CHARACTERISTIC	TEST CONDITIONS		LIMITS			UNITS	
	V <sub>DRA</sub> (V)	V <sub>DD</sub> (V)	All Types				
			Min.	Typ.*	Max.		
Minimum Data Retention Voltage, V <sub>DRA</sub>	—	—	—	1.5	2	V	
Data Retention Quiescent Current, I <sub>DD</sub>	2	—	—	2	10	μA	
L2 Types L3 Types		—	—	5	50		
Chip Deselect to Data Retention Time, t <sub>CDR</sub>	—	5	600	—	—	ns	
Recovery to Normal Operation Time, t <sub>RC</sub>	—	5	600	—	—		
V <sub>DD</sub> to V <sub>DRA</sub> Rise and Fall Time, t <sub>r,tf</sub>	2	5	1	—	—	μs	

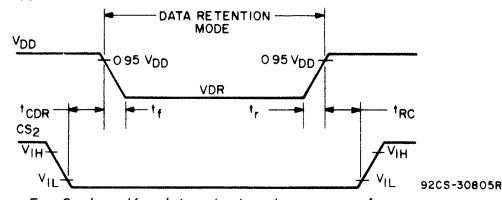
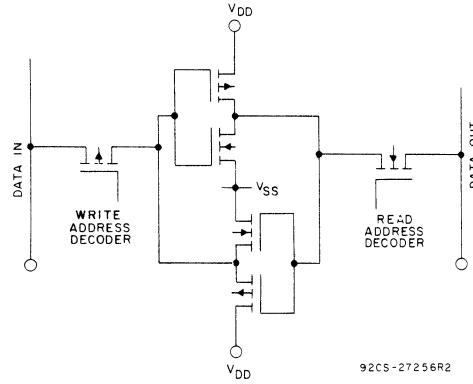
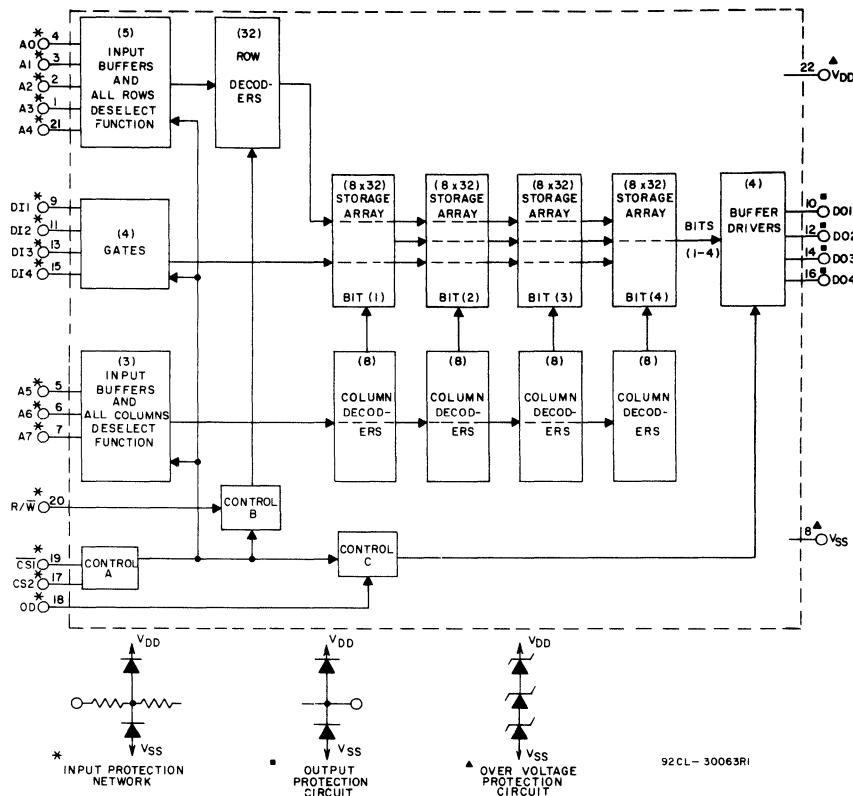
\*Typical values are for  $T_A = 25^\circ\text{C}$ .Fig. 3 - Low V<sub>DD</sub> data retention timing waveforms

Fig. 4 - Memory cell configuration

MWS5101A



*Fig 5 - Functional block diagram for MWS5101A.*

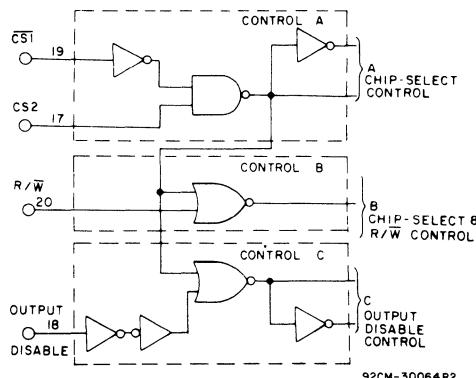


Fig 6 - Logic diagram of controls for MWS5101A.